

<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>		Attorney Docket Number	23-69853-01
		Application Number	10/727,062
		Filing Date	December 2, 2003
		First Named Inventor	John G. DeSteese
		Art Unit	1795
		Examiner Name	Jeffrey Thomas Barton

**U.S. PATENT DOCUMENTS**

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**FOREIGN PATENT DOCUMENTS**

Examiner's Initials*	Cite No. (optional)	Country	Number	Date	Name of Applicant or Patente

**OTHER DOCUMENTS**

	Bottner, H., "Thermoelectric Micro Devices: Current State, Recent Developments and Future Aspects for Technological Progress and Applications," <i>Proc. 21st Int. Conf. Thermoelectronics, Long Beach, CA</i> , pp. 511-518 (August 25-29, 2002).
	Final Office action from the U.S. Patent and Trademark Office for U.S. Patent Application No. 10/726,744, dated April 13, 2009.
	Kim, D.-H. et al., "Effect of deposition temperature on the structural and thermoelectric properties of bismuth telluride thin films grown by co-sputtering," <i>Thin Solid Films</i> , Vol. 510, pp. 148-153 (2006).
	Office action from the U.S. Patent and Trademark Office in U.S. Patent Application No. 10/581,281, dated April 30, 2009.
	Sun, C.W. et al., "Crystallization behavior of non-stoichiometric Ge-Bi-Te ternary phase change materials for PRAM application," <i>J. Phys. Condens. Matter</i> , Vol. 19, 446004, 9 pages (2007).

EXAMINER SIGNATURE:	DATE CONSIDERED:
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\* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.